



100% Material Declaration Data Sheet PDG8

PK118 (v1.3) November 12, 2013

Material Declaration Data Sheet

Average Weight: 0.528 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.006650	1.26%
	Silicon	7440-21-3	100.00		0.006653	
Die Attach Material					0.001980	0.37%
	Resin	Trade Secret	21.00		0.000415	
	Silver	7440-22-4	70.00		0.001383	
	Metal Oxide	Trade Secret	3.00		0.000059	
	Amine	Trade Secret	3.00		0.000059	
	Gamma Butyrolactone	Trade Secret	3.00		0.000059	
Mold Compound					0.318240	60.31%
	Resin Type Ortho Cresol Novolac	Trade Secret	13.50		0.042962	
	SiO2	60676-86-0	86.50		0.275278	
Leadframe					0.189840	35.98%
	Copper	7440-50-8	97.50		0.185099	
	Iron	7439-89-6	2.35		0.004461	
	Phosphorus	7723-14-0	0.03		0.000057	
	Zinc	7440-66-6	0.12		0.000228	
Leadframe Plating					0.001350	0.26%
	Silver	7440-22-4	100.00		0.001350	
Bond Wire					0.000410	0.08%
	Gold	7440-57-5	100.00		0.000414	
Ext. Plating					0.009160	1.74%
	Tin	7440-31-5	100.00		0.009164	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/08/06	1.0	Initial release.
7/05/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.
11/12/06	1.3	New epoxy mold compound composition